Hybrid 8j309 Traveler

May 4, 2000

1 Connectivity

Repairs on shorts:
Fixes for opens:

2 Chips

The following chips were assembled on this hybrid (in the order that the chips get read out):
Hybrid 8J309 has die: 156-055 156-058 156-059 156-061 156-008 156-009 156-013 156-014

3 Data Analysis Summary

The following summarizes the findings of the Burn-in data analysis program. The first chip in the readout name is numbered 0.

```
% Hybrid 8j309 classification info. Created 11:24:27 05/03/00

Hybrid 8j309 quality: fair
Chip classification: good good good good good fair fair good
Bad channels (chip-channel): 5-95 6-2
Bad cells: none
Random bad capacitors (chip-cell-channel): 5-17-114 5-30-114 5-34-114
   5-37-114 5-39-114 5-4-114 5-4-115 5-41-114 5-5-114
Channels at pedestal needed for DCMS: 31.7 30.7 32.3 29.6 30.7 28.7 29.6 30.7
```

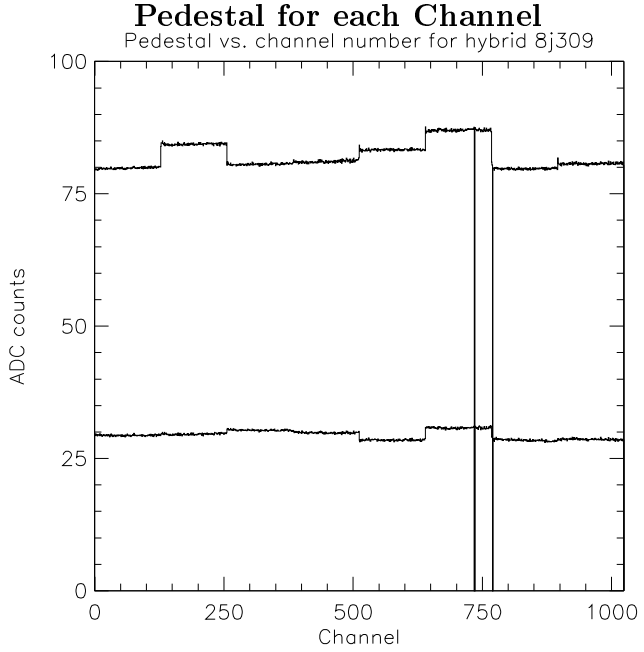
4 Comments

HV tested.

5 Pedestal

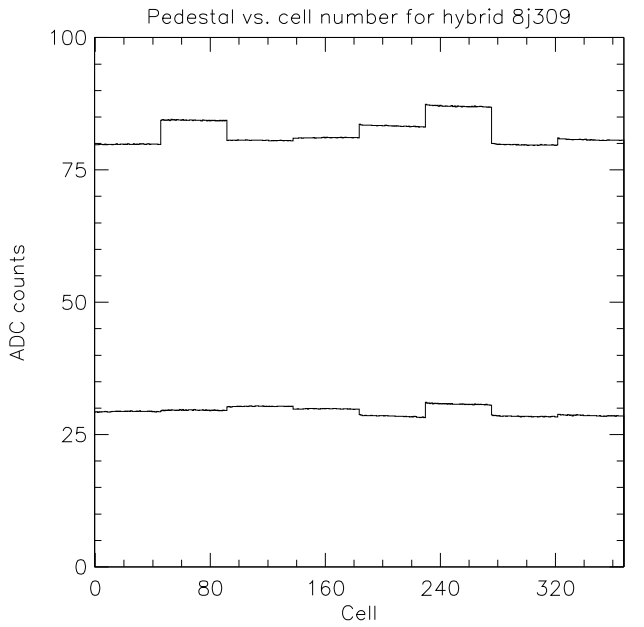
The following plot shows the pedestals vs. channel number with and without charge injection:

Pedestal for each Channel



The following plot shows the average pedestal vs. pipeline cell ID with and without charge injection. The x-axis is cell ID offset by 46 for each chip. Thus cell ID 5 for chip 1 is at x=5, chip 2 at x=51, chip 3 at x=97, etc.

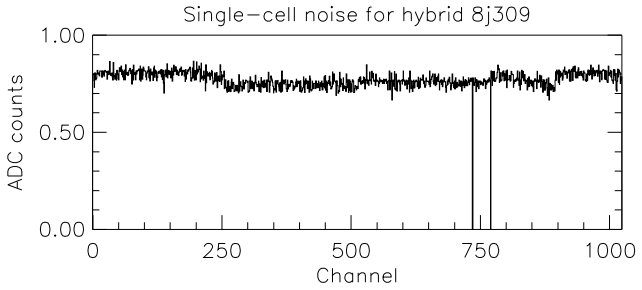
Pedestal vs. Pipeline Cell ID

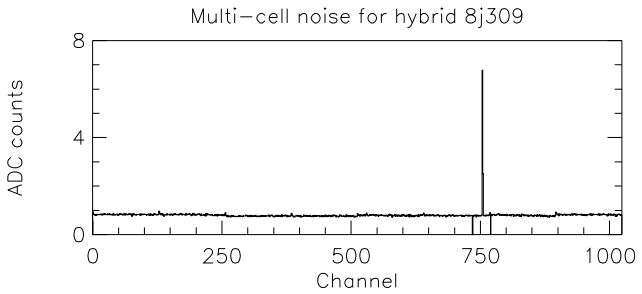


6 Noise

The following plots show the single-cell and multi-cell RMS noise:

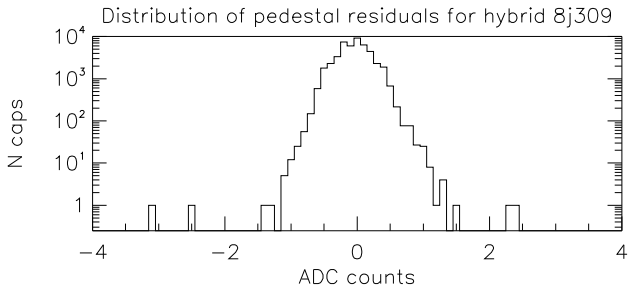
RMS Noise

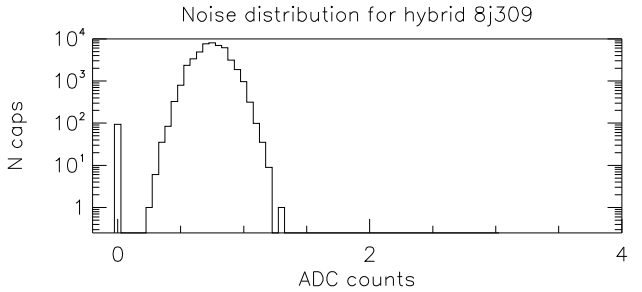




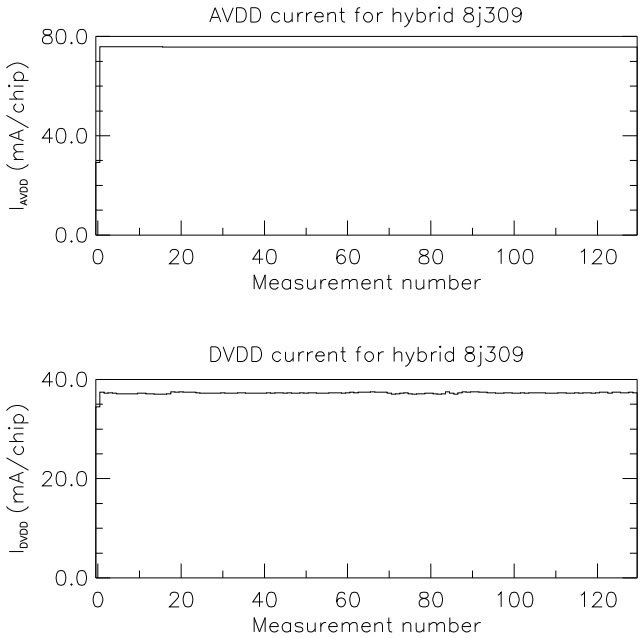
The following are histograms of the pedestal of each pipeline capacitor relative to the chip average (top); and the RMS noise of each capacitor (bottom):

Distribution of Pedestals and Noise





7 Currents

The following plots show the supply currents per chip as a function of measurment number. Currents are measured approximately every 10 minutes:

Supply Currents During Burn-in